

CERN Accelerator School

"Superconductivity for Accelerators"

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Heat transfer and cooling techniques at low temperature

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Outline

- Heat transfer at low temperature (Lecture 1)
 - Conduction
 - Radiation
 - Convection

- Cooling techniques at low temperature (Lecture 2)
 - Different classifications of system with respect to cooling
 - Different methods of cooling
 - Some examples



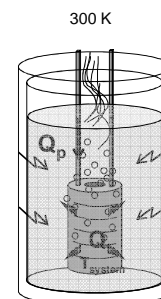
Heat transfer at low temperature (Lecture 1)

- Content
 - Review of different fundamental modes of heat transfer
 - Specificity to the low temperature domain
 - Some practical cases
 - Useful data and references
- Not covered by this lecture
 - Thermodynamics
 - Properties of materials
 - Superfluid helium heat transfer
 - Production of cryogenes
- Present until the end of the school, do not hesitate to ask.



Cooling to low temperature (1/2)

- Primary goal : maintain a system at a temperature $T \ll$ room temperature
 - Thermal stability in steady-state regime $\rightarrow T_{\text{system}} \approx \text{constant}$
 - Protecting your system against transient events $\rightarrow T_{\text{system}} < T_{\text{max}}$
- System defined by thermophysical properties
 - Density (kg/m^3), Heat capacity ($\text{J}/\text{kg}\cdot\text{K}$), Thermal conductivity ($\text{W}/\text{m}\cdot\text{K}$)...
- System subjected to permanent heat input (heat losses), Q_p
 - Thermal radiation (room temperature to T_{system})
 - Conduction through supports, current leads, ...
 - Internal dissipation (Joule effect, AC losses, beam losses...)
- System subjected to transient heat perturbation, Q_t
 - Quench of a superconducting cavity or magnet
- Cooling power provided, Q_R
- In the system design at low temperature conditions
 - Minimize heat input : Minimization of the heat transfer at constant ΔT
 - Maximize heat extraction : Minimization of ΔT at a constant heat transfer



Cooling to low temperature (2/2)

- Three modes of heat transfer

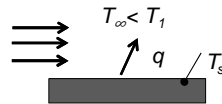
– Conduction: heat transferred in solid or fluid at rest

$$q = -k(T)\vec{\nabla}T$$



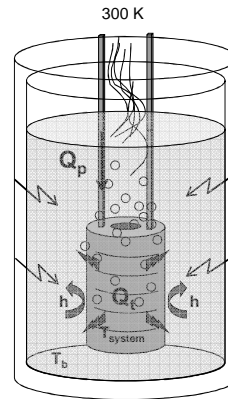
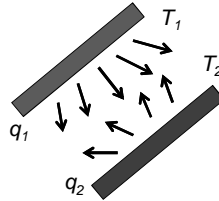
– Convection: heat transferred by movement of fluid

$$q = hA(T_s - T_\infty)$$



– Radiation : Heat transferred by electromagnetic wave

$$q = \varepsilon \cdot \sigma \cdot (T_2^4 - T_1^4)$$



Outline| Conduction

- Heat transfer at low temperature

(Lecture 1)

– Conduction

- Fourier's law
- Thermal conductivity integral – case of a support
- Thermal resistance
- Thermal contact resistance
- Transient heat conduction
- Conduction in liquid
- Conduction in gas

– Radiation

– Convection



Conduction | Fourier's Law

- Heat transfer without mass transfer in solid, liquid or fluid at rest
- For steady-state regime : Fourier's law $q = -k(T)\vec{\nabla} T$
– Heat is flowing from the hot to the cold source.

- In 1D with constant geometry: $q = -k(T)\frac{dT}{dx} \Rightarrow \frac{Q}{A} = \frac{1}{L} \int_{T_{cold}}^{T_{hot}} k(T) dT$

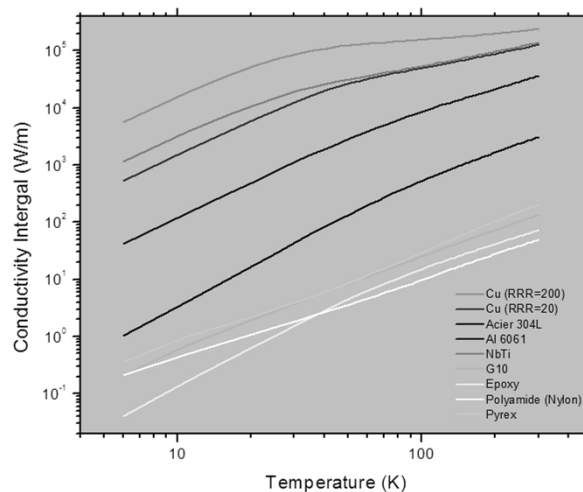


- In 1D with non constant geometry: $q = -k(T)\frac{dT}{dx} \Rightarrow Q \int_0^L \frac{dx}{A} = \int_{T_{cold}}^{T_{hot}} k(T) dT$

- $\int k(T) dT$ is the integral conductivity. Very important since the thermal conductivity varies between room temperature and low temperature



Conduction | Thermal conductivity integral



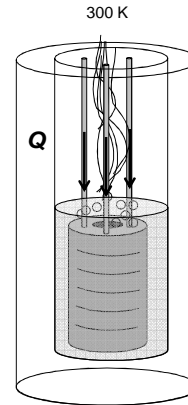
Conduction | Case of a support (1/2)

- Use of conductivity integral
 - Heat leak, temperature profile
- Heat input on the liquid helium bath cooling a magnet?
- If the magnet is suspended by three rods of 304 stainless steel from the 300 K top flange
 - Rods : $\varnothing=10$ mm and $L=1$ m

$$Q_{4K} = \frac{A}{L} \int_{4.2}^{300} k_{SS}(T) dT = \frac{2.3610^{-4}}{1} 3.0710^3 = 0.7 \text{ W}$$

- It corresponds to a consumption of 1 l/h of liquid helium

- If the rods are made of
 - Copper (RRR=20) with a conductivity integral of $1.26 \cdot 10^5$ W/m, then $Q_{4K} \approx 20$ W
 - G10 (Epoxy fiberglass tape) with an integral of 167 W/m, then $Q_{4K} \approx 26$ mW



Conduction | Case of a support (2/2)

- To reduce the heat load on the helium bath
 - Heat interception with another cold source at an intermediate constant temperature (thermalization)
 - Boiling nitrogen or temperature regulated cold stage of cryocoolers
- If the interception is made with boiling nitrogen @ 77 K at 1/3 of the length from the top

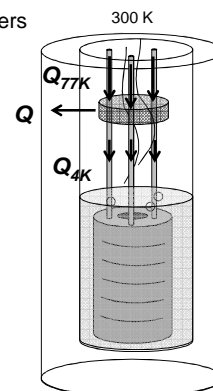
$$Q_{4K} = \frac{A}{L} \int_{4.2}^{77} k(T) dT = \frac{2.3610^{-4}}{0.75} 325 = 0.1 \text{ W}$$

which corresponds to a consumption of liquid helium divided by 7!

$$Q_{77K} = \frac{A}{L} \int_{77}^{300} k(T) dT = \frac{2.3610^{-4}}{0.25} 2.7510^3 = 2.6 \text{ W}$$

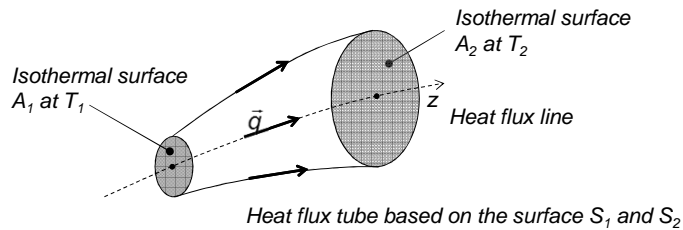
which corresponds to a consumption of liquid nitrogen of 0.06 l/h

- Optimization depends on many parameters such as the thermalization temperature, the properties of the materials, the geometry...



Conduction | Thermal resistance (1/2)

- In the case of steady-state and without internal dissipation, a thermal resistance can be defined:



$$Q \int_{z_1}^{z_2} \frac{dz}{A(z)} = - \int_{T_1}^{T_2} k(T) dT = \bar{k}(T_1 - T_2) \Rightarrow R_{th} = \frac{T_1 - T_2}{Q} = \frac{1}{\bar{k}} \int_{z_1}^{z_2} \frac{dz}{A(z)} \left[\frac{K}{W} \right]$$

- For a slab with constant section $R_{th} = \frac{L}{kA}$, a cylinder $R_{th} = \frac{\ln(R_2/R_1)}{k2\pi L}$
- For a convective boundary $R_{th} = \frac{1}{hA}$

Conduction | Thermal resistance (2/2)

- Case of a composite wall, R_{th} are in series so $R_{total} = \sum R_i$
- Case of a composite wall with heat transfer coefficients at boundaries

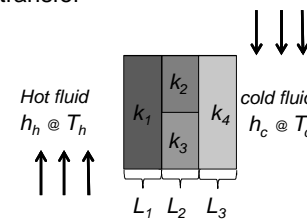
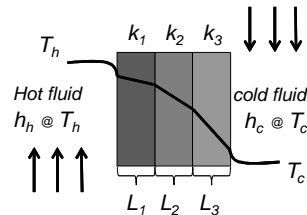
$$Q = \frac{T_h - T_c}{\sum R_i} = A \frac{T_h - T_c}{(1/h_h) + (L_1/\bar{k}_1) + (L_2/\bar{k}_2) + (L_3/\bar{k}_3) + (1/h_c)}$$

- In the case of parallel components
 - R_{th} are in parallel so $1/R_{total} = \sum 1/R_i$

- Case of a composite (series/parallel) wall with heat transfer coefficients at boundaries

$$Q = A \frac{T_h - T_c}{(1/h_h) + (L_1/\bar{k}_1) + (2L_2/(\bar{k}_2 + \bar{k}_3)) + (L_4/\bar{k}_4) + (1/h_c)}$$

$$L_2 = L_3 \text{ and } A_2 = A_3 = \frac{A}{2}$$



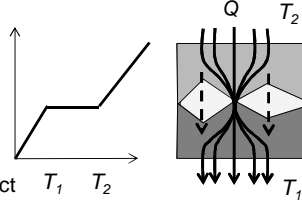
Conduction | Contact resistance (1/2)

- Imperfect contact characterized by a temperature drop resulting from
 - Local contact creating constriction of the flux lines
 - Phonon scattering at the solid-solid contact (Kapitza resistance)
 - Heat transfer via interstitial elements

- Overall thermal resistance is defined $R_c = \frac{T_2 - T_1}{Q}$

- R_c depends on surface condition, nature of the materials, temperature, interstitial materials, compression force...

- Proportional to force, not to pressure (number of contact points increases with force)
- Reduces with increasing force
- Increases by several orders of magnitude from 200 to 20 K

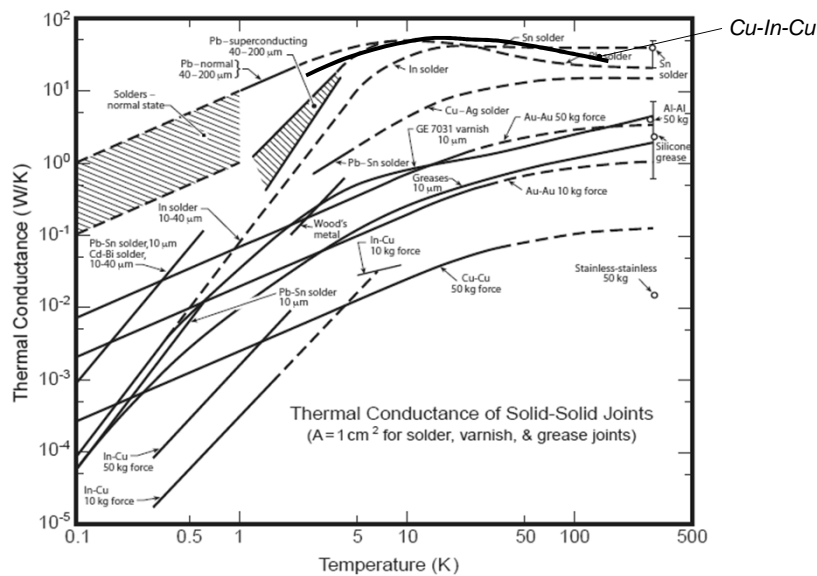


⚠ At low temperature R_c can be the largest thermal resistance

- Can be reduced by strong tightening or Inserting conductive and malleable fillers (charged grease, indium or coatings)
- Modeling is very difficult, the use of experimental data is recommended



Conduction | Contact resistance (2/2)



Ekin JW. Experimental Techniques for Low Temperature Measurements. Oxford: Oxford University Press; 2006.



Conduction | Transient – Time constant

- Energy conservation equation

$$\rho C \frac{\partial T}{\partial t} = \nabla \cdot (-k(T) \nabla T) + Q \quad \left[\frac{W}{m^3} \right]$$

Change of energy Heat conduction Volume heat generation

- In 1D with constant coefficient, one can identify thermal diffusivity:

$$\frac{\partial T}{\partial t} = \frac{k}{\rho C} \frac{\partial^2 T}{\partial x^2} + Q' \Rightarrow D = \frac{k}{\rho C} \quad \left[\frac{m^2}{s} \right]$$

- And a time constant $\tau \approx \frac{4 L^2}{\pi^2 D}$ ($T=0.63T_{final}$) for $T=0.95T_{final}$ then $t=3\tau$

Thermal diffusivity in cm²/s

	300 K	77 K	4 K
Cu OFHC (RRR=150)	1.2	3.2	11700
Pur Al (RRR=800)	1	4.7	42000
Commercial Al (6061)	0.7	1.3	1200
SS 304 L	0.04	0.05	0.15



Conduction in liquid

- As at room temperature, liquids are bad thermal conductor at low temperature
- Conductivity decreases with temperature
- Conduction in liquid is negligible compared to convection or phase change phenomena
- Except for superfluid helium, where the $k_{eq} \sim 1000$ higher than high purity copper

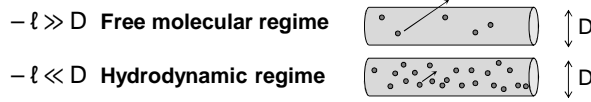
Thermal conductivity of some cryogens at atmospheric pressure (W/m.K)

O ₂ (T=90 K)	N ₂ (T=77 K)	H ₂ (T=20 K)	He (T=4.2 K)
0.152	0.14	0.072	0.019



Conduction in gas (1/3)

- Two regimes depending on the ratio of the mean free path of the molecule (ℓ) and the distance between the two surfaces (D) involved in the heat transfer



- The mean free path for ideal gas $\lambda = \frac{RT}{\sqrt{2}\pi d^2 N_A \rho}$
 - R=universal gas constant = 8.31 J / mol.K
 - N_A =Avogadro's number = 6.02 10^{23} /mol
 - d=Molecule diameter
- At constant temperature for a material,
 - The **free molecular regime** is obtained for the low residual pressure
 - Heat transfer depends on the residual gas pressure and independent of D
 - The **hydrodynamic regime** is obtained for high residual gas pressure
 - Heat transfer is independent of pressure and described by a Fourier law



Conduction in gas (2/3)

- Free molecular regime : **Kennard's law**

$$Q = A\alpha \left(\frac{\gamma+1}{\gamma-1} \right) \sqrt{\frac{R}{8\pi M}} \frac{\Delta T}{\sqrt{T}} p \quad \text{with} \quad \gamma = \frac{C_p}{C_v}$$

- α is the accommodation coefficient which relates the degree of thermal equilibrium between the gas and the wall
- Prediction for helium $\alpha \leq 0.5$, argon $\alpha \sim 0.78$ and nitrogen $\alpha \sim 0.78$

- Hydrodynamic regime : **Kinetic theory** $q = -k \nabla T$

$$k = \frac{1}{3} \ell v C \quad \{v : \text{mean velocity of the molecules}\}$$

Thermal conductivity k [mWm⁻¹ K⁻¹] @ 1 atm

T [K]	⁴ He	H ₂	N ₂
300	150.7	176.9	25.8
75*	62.4	51.6	7.23
20	25.9	15.7	
5	9.7		

Cryogenic Heat transfer,
R.F. Barron,
Taylor&Francis, 1999

V. C. Johnson, A
Compendium of the
Properties of Materials at
Low Temperatures, Wadd
Tech. Rep. 60-56, 1960)



Conduction in gas (3/3)

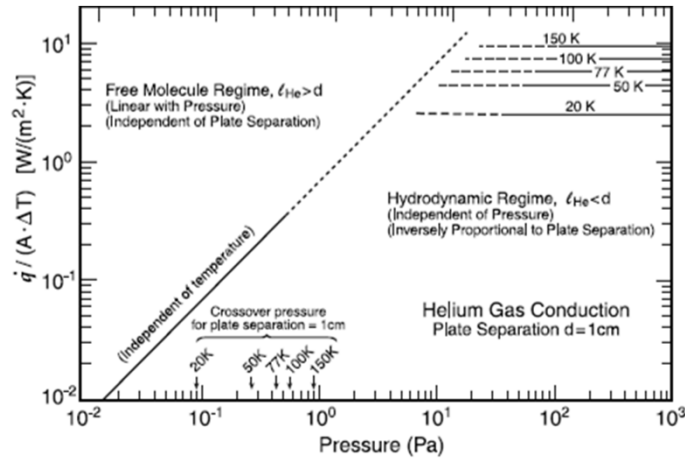


FIG. 2.2 Heat conduction through helium gas between two parallel copper plates spaced 1 cm apart as a function of pressure at various gas temperatures. The heat conduction shows a linear dependence on gas pressure below about 1 Pa and no dependence at higher pressure. The crossover pressure is inversely proportional to the plate separation d (determined by setting $l = d$ in Eq. 2.5).

From *Experimental Techniques in Low Temperature Measurements*, Jack W. Ekin, Oxford Univ. Press (2006, 2007)



Outline | Radiation

- Heat transfer at low temperature (Lecture 1)
 - Conduction
 - Radiation
 - Introduction
 - Blackbody radiation
 - Surface emission
 - Emissivity
 - Radiation exchange between two surfaces
 - Shielding
 - Multi-layer insulation
 - Convection

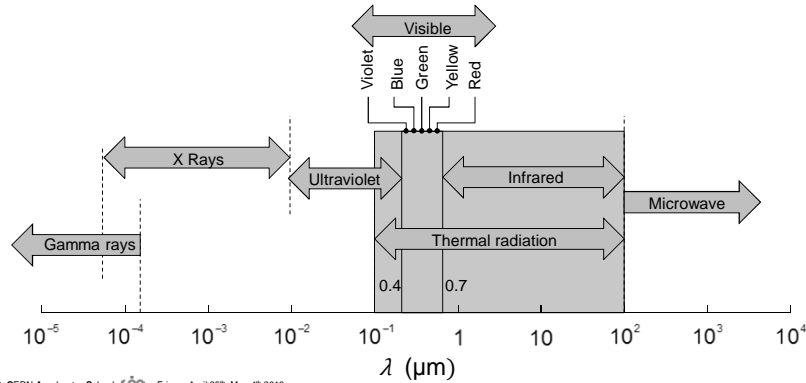


Radiation | Introduction (1/2)

- Heat transfer by electromagnetic waves
- Radiated energy propagates through a medium with wave length λ

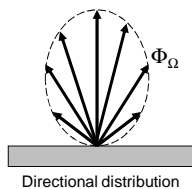
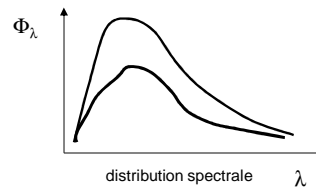
$$\lambda = \frac{c}{\nu} \quad \begin{cases} c = \text{speed of light in the medium (m/s)} \\ \nu = \text{frequency (s}^{-1}\text{)} \end{cases}$$

- Wave length associated with thermal radiation: 0.1 μm to 100 μm



Radiation | Introduction (2/2)

- Heat transfer depends on the wave length, λ
 - Emitted radiation consists of a continuous non uniform distribution of monochromatic components Φ_λ
 - Spectral distribution and the magnitude depend on the nature and the temperature of the emitting surface



- Heat transfer depends on the direction
 - Directional distribution of the emitted radiation

- To characterize radiation heat transfer both spectral and directional dependence (as a function of temperature and surface) must to be known

Radiation | Blackbody radiation

- A perfect emitter and an absorber
 - Absorbs all incident radiation regardless of the wave length and direction
 - At a prescribed temperature and wave length, emission is maximum
 - Diffuse emitter (no directional dependence)
- Emissive power (Emittance) : Planck distribution

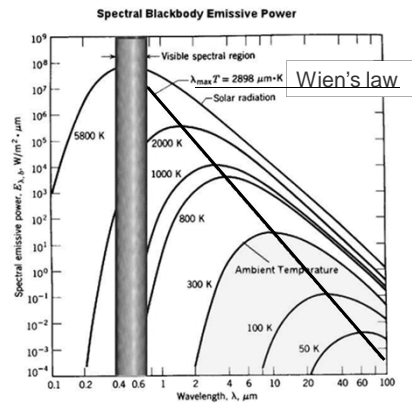
$$E_{\lambda}^0 = \frac{C_1}{\lambda^5 \left(e^{C_2/\lambda T} - 1 \right)}$$

$$\begin{cases} C_1 = 2\pi h C_0^2 = 3.74210^{-16} \text{ Wm}^4/\text{m}^2 \\ C_2 = h C_0 / k = 1.438810^{-16} \text{ Wm}^2/\text{K} \end{cases}$$

- Stefan-Boltzmann Law

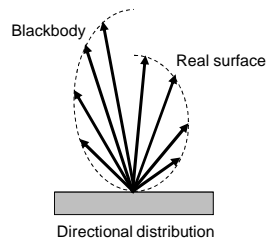
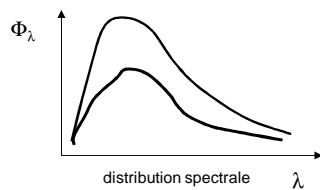
$$E^0 = \int_0^{\infty} \frac{C_1}{\lambda^5 \left(e^{C_2/\lambda T} - 1 \right)} d\lambda = \sigma T^4$$

with $\sigma = 5.67 \cdot 10^{-8} \text{ W/m}^2\text{K}^4$



Radiation | Surface emission

- From a perfect emitter to a real surface
 - Emissivity is the ratio of the real surface to the blackbody radiation intensity
 - A spectral, monochromatic directional emissivity can be defined as $\epsilon(\lambda, \theta, \phi, T)$
 - A spectral emissivity as $\epsilon(\lambda, T)$
 - A total emissivity as $\epsilon(T)$



- Special case (approximation)
 - Grey body : $\epsilon(\theta, \phi, T)$ independent of λ
 - Diffuse body : $\epsilon(\lambda, T)$ independent of direction
- Real emissivity depends on the direction and wavelength

Radiation | Emissivity (1/2)

- Emissivity decreases with temperature
- Emissivity increases with oxidation, impurities, dirt
- To achieve the lowest emissivity value
 - Highly polished surface
 - High conductivity surfaces (gold, silver copper or aluminum)
- Many data can be found in the literature

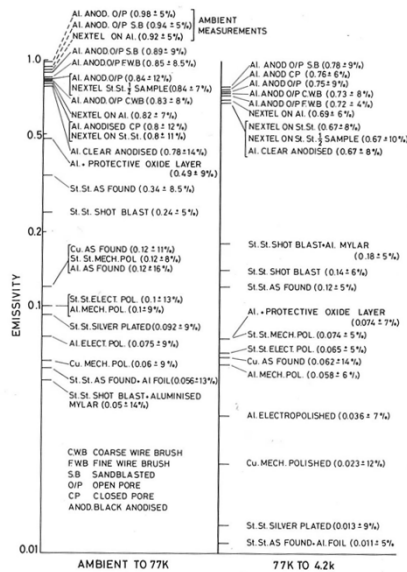
Total emissivity of various metal

	300 K	78 K	4,2 K
3M Black paint (80 μm) on copper surface	0,94	0,91	0,89
Polished Aluminum (33 μm in rough.)	0,05	0,23	0,018
Polished Copper (41 μm in rough.)	0,10	0,07	0,05
304 Polished Stainless steel (27 μm in rough.)	0,17	0,13	0,08

K H Hawks & W Cottingham: Total Normal Emittances of Some Real Surfaces at Cryogenic Temperatures, Advances In Cryogenic Engineering, Vol 16, 1970, pp 467-474.



Radiation | Emissivity (2/2)



Obert W. Emissivity measurements of metallic surfaces used in cryogenic applications. Adv. Cryo. Eng. 27, Plenum Press 1982 p. 293-300



Radiation | Radiation exchange between two surfaces

- Fraction of the radiation leaving surface i and intercepting surface j

View factor F_{ij}

$$F_{11}=0; F_{12}=1 \quad \begin{array}{c} \textcircled{1} \\ \textcircled{2} \end{array} \quad F_{22}=1-A_1/A_2; F_{21}=A_1/A_2 \quad q_{12} = \varepsilon_1 \sigma A_1 (T_1^4 - T_2^4)$$

-Reciprocity relation $A_1 F_{ij} = A_j F_{ji}$

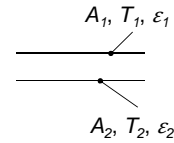
- Heat exchange between diffuse grey two-surface enclosure

$$q_{12} = \frac{\sigma(T_1^4 - T_2^4)}{\frac{1-\varepsilon_1}{\varepsilon_1 A_1} + \frac{1}{A_1 F_{12}} + \frac{1-\varepsilon_2}{\varepsilon_2 A_2}}$$

Large parallel plates

$$A = A_1 = A_2 \\ F_{12} = 1$$

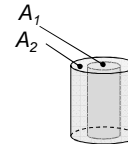
$$q_{12} = \frac{\sigma A_1 (T_1^4 - T_2^4)}{\frac{1}{\varepsilon_1} + \frac{1}{\varepsilon_2} - 1}$$



Long concentric cylinders

$$\frac{A_1}{A_2} = \frac{r_1}{r_2} \\ F_{12} = 1$$

$$q_{12} = \frac{\sigma A_1 (T_1^4 - T_2^4)}{\frac{1}{\varepsilon_1} + \frac{1-\varepsilon_2}{\varepsilon_2} \left(\frac{r_1}{r_2}\right)}$$



Radiation | Shielding at low temperature

- Blackbody** heat transfer from room temperature

- From 300 K to 77 K : $q=457 \text{ W/m}^2$
- From 300 K to 4.2 K : $q=459 \text{ W/m}^2$

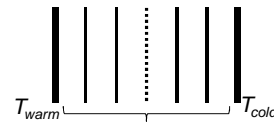
$$q = \sigma (T_{\text{warm}}^4 - T_{\text{cold}}^4)$$

- Blackbody** heat transfer from Nitrogen temperature

- From 77 K to 4.2 K : $q=2 \text{ W/m}^2$ ($q \sim 200$ times lower than 300 K)

- To reduce heat load at low temperature : intermediate surface at intermediate temperature

$$q = \frac{\varepsilon \sigma}{2 - \varepsilon} (T_{\text{warm}}^4 - T_{\text{cold}}^4) \quad q = \frac{1}{2} \frac{\sigma \varepsilon}{2 - \varepsilon} (T_{\text{warm}}^4 - T_{\text{cold}}^4) \quad q = \frac{1}{n+1} \frac{\sigma \varepsilon}{2 - \varepsilon} (T_{\text{warm}}^4 - T_{\text{cold}}^4)$$



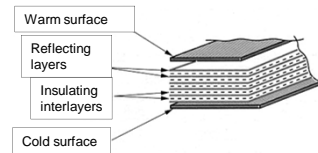
$$T^4 = \frac{T_{\text{warm}}^4 - T_{\text{cold}}^4}{2}$$

$$T_i^4 = T_{\text{cold}}^4 + \frac{T_{\text{warm}}^4 - T_{\text{cold}}^4}{i+1}$$

Radiation | Multi-layer insulation (1/2)

- **MLI or Superinsulation**
 - Reflecting layers to reduce heat transfer by radiation
 - Insulating interlayer to reduce heat transfer between reflecting layers
 - High vacuum to reduce convection and residual gas conduction

- **MLI materials**
 - Reflecting layers: mostly aluminum metallized Mylar films (both sides)
 - Thermal conductivity anisotropy
 - Insulating interlayer : mostly net of polyester or fiber glass, paper silk



- Heat transfer parallel to the layers is several order of magnitude higher than normal to layers due to the pure aluminum
- Bad vacuum than residual conduction becomes important
- Low temperature boundary (77 K to 4 K)
 - Radiation negligible, heat transfer dominated by conduction
- High temperature boundary (300 K to 80 K)
 - Heat transfer dominated by radiation : MLI efficient



Radiation | Multi-layer insulation (2/2)

- Typical value of heat transfer for 20 layers
 - 1 to 3 W/m² from 300 K to 80 K (5 W/m² if compressed)
 - Lower than 100 mW/m² between 80 K and 4 K

- To optimize the use of MLI
 - Number of layers/cm max : 20-30
 - Isothermal contact points



- No gaps to have uniform heat transfer
- No mechanical stress → contact point increases the conduction
- Perforated MLI to have low residual pressure

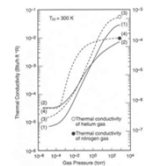
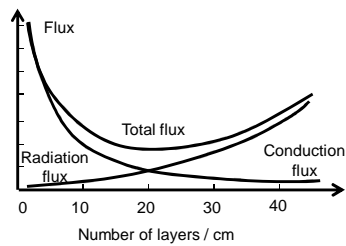


Figure 3.10 Thermal conductivity of insulation composition as a function of gas pressure
 (1) All data of Pongratz Paper Surface Metall. Co. = 20 K (from Arthur D. Little, Inc., Report 4000-000, July 1962, p. 26)
 (2) All data of Pongratz Paper Surface Metall. Co. = 20 K (from Pongratz Paper Surface Metall. Co., Report 4000-000, July 1962, p. 26)
 (3) Data of Pongratz Paper Surface Metall. Co. = 20 K (from Pongratz Paper Surface Metall. Co., Report 4000-000, July 1962, p. 26)
 (4) Data of Pongratz Paper Surface Metall. Co. = 20 K (from Pongratz Paper Surface Metall. Co., Report 4000-000, July 1962, p. 26)
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 (7) Data of Pongratz Paper Surface Metall. Co. = 20 K (from Pongratz Paper Surface Metall. Co., Report 4000-000, July 1962, p. 26)
 (8) Data of Pongratz Paper Surface Metall. Co. = 20 K (from Pongratz Paper Surface Metall. Co., Report 4000-000, July 1962, p. 26)

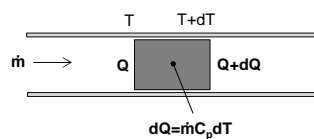


Outline | Convection

- Heat transfer at low temperature (Lecture 1)
 - Conduction
 - Radiation
 - Convection
 - Introduction to single phase convection
 - Natural convection
 - Forced convection
 - Introduction to boiling
 - Boiling heat transfer
 - Two-phase convection

Convection | Introduction to single phase flow (1/4)

- Heat is transferred in the fluid by the movement of matter
 - Quantity of energy is advected within the fluid



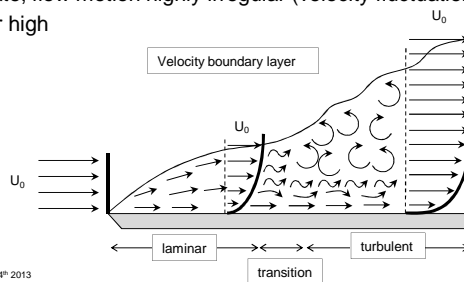
- The movement of matter can be created externally by a pump or a pressurization system: **forced convection**
- Equations for convection in the Boussinesq approximation (Steady-State)

Continuity	$\nabla \cdot \mathbf{v} = 0$	Dimensionless	$\nabla \cdot \mathbf{v}^* = 0$
Navier-Stokes	$\rho \mathbf{v} \cdot \nabla \mathbf{v} = -\nabla p + \mu \nabla^2 \mathbf{v} + \mathbf{f}$	→	$\mathbf{v}^* \cdot \nabla \mathbf{v}^* = -\nabla p^* + \text{Re}^{-1} \nabla^2 \mathbf{v}^*$
Energy	$\rho C_p \mathbf{v} \cdot \nabla T = k \nabla^2 T + Q$		$\mathbf{v}^* \cdot \nabla T^* = \text{Re}^{-1} \text{Pr}^{-1} \nabla^2 T^*$

- Reynolds number $\text{Re} = \frac{\rho L U}{\mu} = \frac{\text{inertia forces}}{\text{viscous forces}}$ Nature of the flow
- Prandtl number $\text{Pr} = \frac{\mu C_p}{k} = \frac{\text{momentum diffusivity}}{\text{thermal diffusivity}}$ Thermophysical properties of the fluid

Convection | Introduction to single phase flow (2/4)

- Laminar and turbulent regimes
 - Essential to know in which regime the flow is since the surface **heat transfer** and **friction** depend strongly on it
- Laminar regime for $Re < 2300$
 - Viscous forces dominate, flow motion ordered (streamline)
 - Surface heat transfer low
 - Surface friction low
- Turbulent regime for $Re > 5 \cdot 10^5$
 - Inertia forces dominate, flow motion highly irregular (velocity fluctuation)
 - Surface heat transfer high
 - Surface friction high



Convection | Introduction to single phase flow (3/4)

- The fluid movement can be created internally by a decrease or increase of the fluid density or the buoyancy effect: **natural convection**
- Equations for convection in the Boussinesq approximation (Steady-State)

$$\begin{array}{l}
 \text{Continuity} \quad \nabla \cdot \mathbf{v} = 0 \\
 \text{Navier-Stokes} \quad \rho \mathbf{v} \cdot \nabla \mathbf{v} = -\nabla p + \mu \nabla^2 \mathbf{v} + \beta \Delta T \mathbf{g} \xrightarrow{\text{Dimensionless}} \mathbf{v}^* \cdot \nabla \mathbf{v}^* = -\nabla p^* + Re^{-1} \nabla^2 \mathbf{v}^* + Gr Re^{-2} T^* \\
 \text{Energy} \quad \rho C v \cdot \nabla T = k \nabla^2 T \qquad \qquad \qquad \mathbf{v}^* \cdot \nabla T^* = Re^{-1} Pr^{-1} \nabla^2 T^*
 \end{array}$$

$$\text{–Grashof number} \quad Gr = \frac{g \beta \Delta T L^2}{\mu^2} = \frac{\text{buoyancy forces}}{\text{viscous forces}}$$

- When $Gr Re^2 \gg 1$, then forced convection negligible
- If $Gr Re^{-2} \approx 1$, then mixed convection

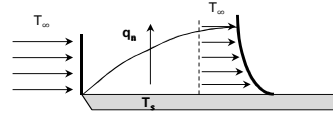
- Gr has the same role for natural convection as Re for forced convection
- Turbulence has a strong effect as in forced convection and reached for

$$Gr \cdot Pr \geq 10^5$$

Convection | Introduction to single phase flow (4/4)

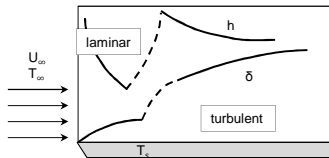
- Heat is transferred to solid elements
 - Quantity of energy transfer in or out of the fluid to the solid
 - Newton's law $q = h(T_s - T_\infty)$

- At the boundary, the local heat flux is $q_n = -k \cdot \nabla T_n$



- Dimensionless, it is the Nusselt number $Nu = \frac{hL}{k} = \frac{\partial T}{\partial n} \Big|_0$

- The Nusselt number is to the thermal boundary as the friction coefficient is to the velocity boundary
- $Nu = f(Re, Pr, L)$ for forced convection and $Nu = f(Gr, Pr, L)$ for natural convection
- Nu different for turbulent or laminar (different correlation)



Convection | Natural convection heat transfer

- Heat flux is computed with correlation $Nu = (Gr, Pr, L)$
 - Thermophysical properties are established at average temperature $T = (T_w + T_\infty)/2$
 - T_w = solid temperature; T_∞ temperature of the fluid
- The simplest correlations are $Nu = c(Gr.Pr)^n$
 - For laminar regime $n = 1/4$
 - Turbulent regime $n = 1/3$
- Few data exist for cryogenic fluid since two-phase phenomena take over
- Results not very different from classic fluids

	c	n
Supercritical helium Vertical orientation Turbulent	0,615	0,258
Liquid Nitrogen different orientations Turbulent	0,14	1/3
Liquid Hydrogen Different configurations turbulent	0,096	0,352

Hilal MA, Boom RW. An experimental investigation of free convection heat transfer in supercritical helium. Int. J Mass Trans. 1980; **23** 697-705.

Clark, J.A. Cryogenic heat transfer Adv. in Heat Transfer 5 (1968) p. 375

Daney DE. Turbulent natural convection of liquid deuterium, hydrogen and nitrogen within enclosed vessels. Int. J Heat Mass Trans. 1976; **19(4)** p. 431-41.

Convection | Forced convection heat transfer

- Heat flux is computed with correlation $Nu=(Re, Pr, L)$
 - Thermophysical properties are established at average temperature $T=(T_s+T_\infty)/2$
- Correlation used for non cryogenic fluid works at low temperature
- Turbulent flow in pipes : The Dittus-Boetler correlation $Nu=0.023Re^{0.8}Pr^{0.4}$
 - Hydrogen : $Nu=0.023Re^{0.8}Pr^{0.4}$

Tatsumoto H, et al. Forced Convection Heat Transfer of Liquid Hydrogen Through a 200-mm Long Heated Tube. *Physics Procedia*. 2012;36(0):1360-5.
 - Supercritical helium : $Nu=0.022Re^{0.8}Pr^{0.4}$

Giarratano PJ, et al. Forced convection heat transfer to subcritical helium I. *Adv. Cryo. Eng.* **19**, Plenum Press; 1974. p. 404-16.
 - Nitrogen : $Nu=0.027Re^{0.8}Pr^{0.14/3} (\mu_l/\mu_w)^{0.14}$

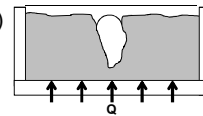
Ohira K, et al. Pressure-drop reduction and heat-transfer deterioration of slush nitrogen in horizontal pipe flow. *Cryogenics*. 2011;51(10):563-74
- Laminar flow in pipes : very rare, excepted in porous media



Convection | Introduction to boiling

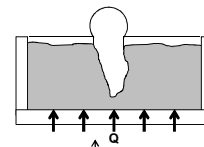
- Heat is transferred between a surface and the fluid by the conjunction of phase change and the vapor bubble movement in the vicinity of the surface

- At the heated surface the fluid must be superheated $T_f > T_{sat}(p)$
- Imperfections in the surface where bubbles can form



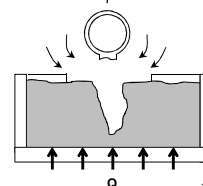
- For bubbles to be stabilized, the pressure inside must exceed the saturation pressure to overcome the surface tension, σ

$$p_v - p_{sat} = \frac{2}{r} \sigma$$



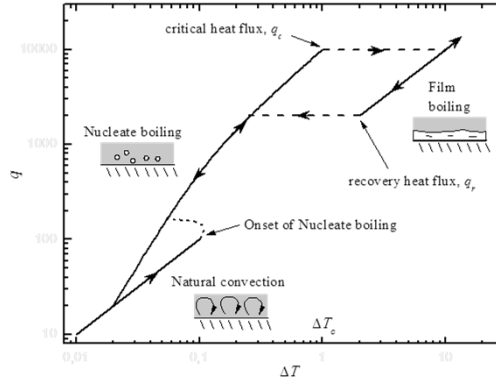
- Heat transfer combines natural convection in the liquid, latent heat due to the bubble formation and the bubble hydrodynamics

- Depends on the bubble growth rate, detachment frequency, number of nucleation sites, surface conditions...



Convection | Pool boiling – boiling curve

- Horizontal flat surface with liquid near saturation



Clark JA. Cryogenic heat transfer. In: *Advances in Heat Transfer*. New York: Academic Press; 1969. p. 325-517.

Smith RV. Review of heat transfer to helium I. *Cryogenics*. 1969; **9**(1):11-9.

Kida M, et al. Pool-Boiling Heat Transfer in Liquid Nitrogen. *Journal of Nuclear Science and Technology*. 1981; **18**(7):501-13.

Shirai Y, et al. Boiling heat transfer from a horizontal flat plate in a pool of liquid hydrogen. *Cryogenics*. 2010; **50**(6-7):410-6.

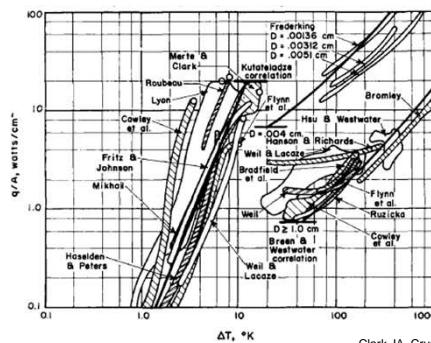
	ΔT_c (K)	q_c (kW/m ²)	q_r (kW/m ²)
Helium	1	10	
Nitrogen	10	100	
Hydrogen	5	100	10

Convection | Pool boiling heat transfer (1/2)

- Heat transfer in nucleate boiling : Kutateladze correlation $q=f(p).\Delta T^{2.5}$

$$\frac{h}{k_f} \left(\frac{\sigma}{g\rho_f} \right)^{1/2} = 3.25 \cdot 10^{-4} \left[\frac{q C_{pl} \rho_l}{h_{lv} \rho_v k_f} \left(\frac{\sigma}{g\rho_f} \right)^{1/2} \right]^{0.6} \left[g \left(\frac{\rho_l}{\mu_l} \right)^2 \left(\frac{\sigma}{g\rho_f} \right)^{3/2} \right]^{0.125} \left(\frac{p}{(\sigma g \rho_f)^{1/2}} \right)^{3/2}$$

- Depends on the orientation, fluid, pressure, surface state, ...
- Works for most cryogenic fluids within one order of magnitude



Pool boiling for Nitrogen at 1 bar

Convection | Pool boiling heat transfer (2/2)

- Critical heat flux : Correlation of Kutateladze

$$q_c = 0.16 h_{lv} \rho_v^{1/2} [\sigma g (\rho_l - \rho_v)]^{1/4}$$

- Works for helium, nitrogen, oxygen and hydrogen

Shirai Y, et al. Boiling heat transfer from a horizontal flat plate in a pool of liquid hydrogen. *Cryogenics*. 2010;50(6-7):410-6.
Lyon DN. Boiling heat transfer and peak nucleate boiling fluxes in saturated liquid helium between the l and critical temperatures. 10, 1964. p. 371-9.

- Not valid when the fluid is sub-cooled *i.e.* pressure above the heated surface is higher than saturated pressure

$$\frac{q_{c,sub}}{q_{c,sat}} = 0.2 \left[1 + 0.15 \left(\frac{\rho_l}{\rho_v} \right)^{3/4} \frac{C_p \Delta T_{sub}}{h_{lv}} \sigma \right]$$

Kirichenko YA, et al. Heat transfer in subcooled liquid cryogens. *Cryogenics*. 1983;23(4):209-11.

- Film boiling : An order of magnitude lower heat transfer coefficient



Convection | Two-phase flow heat transfer

- Two-phase forced flow heat transfer

- Modeling must take into account the boiling heat transfer depending on the surface heat transfer, and the forced convection depending on the vapor quality ($x=\dot{m}_v/\dot{m}_t$) and the mass flow rate (\dot{m}_t)
- Boiling tends to be dominant for low quality and high heat flux
- Forced convection tends to be dominant for large vapor quality and mass flow rate
- Several general correlations and specific to cryogenic fluid exit
- Better to try more than one to evaluate the heat transfer rate

- Superposition method (Chen)

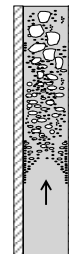
$$h_{TP} = h_{nb} + h_f$$

- Intensification model (Shah)

$$h_{TP} = E \cdot h_f$$

- Asymptotic model (Liu et Winterton n=2)

$$h_{TP} = \left[(F_{nb} h_{nb})^n + (F_f h_f)^n \right]^{1/n}$$

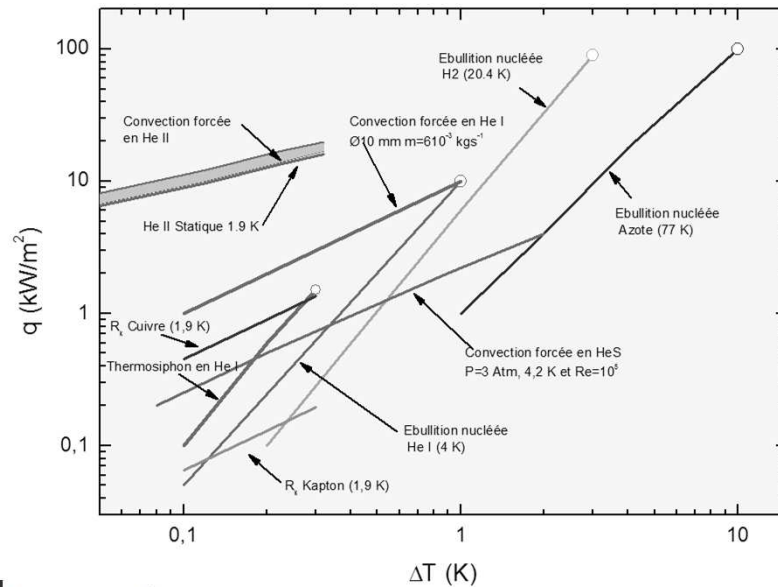


- The Steiner-Taborek (n=3) correlation is considered as the most accurate including the cryogenic fluids (helium, hydrogen, nitrogen, oxygen, ...)

CHEN J.C. Correlation of boiling heat transfer to saturated fluids in convective boiling. *Ind. Eng. Chem. Proc. Des. Dev.*, 5, 3 (1966), 322-339.
SHAH M.M. – A new correlation for heat transfer during boiling flow through pipes. *ASHRAE Trans*, 82, 2 (1976), 66-86.
Steiner H, Taborek J. Flow boiling heat transfer in vertical tubes correlated with an asymptotic model. *Heat Transfer Engineering*. 1992;13(2):43-69.



Cooling modes | Comparison



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Lecture 1 | References & Acknowledgement

- **Journal**
 - *Cryogenics*, Elsevier Science (<http://www.journals.elsevier.com/cryogenics/>)
- **Monographs**
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 - J.W. Ekin, Experimental techniques for low temperature measurements. Oxford University Press; 2006
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 - T.M. Flynn, Cryogenic Engineering, Marcel Dekker, NY, 1997
 - S.W. Van Sciver, Helium Cryogenics 2nd, Springer, NY, 2012
 - Handbook of cryogenic engineering, ed. J.G. Weisend, Taylor&Francis, 1998
- **Conference Proceedings**
 - Advances in Cryogenic Engineering, Volumes 1 – 57, proceedings of the Cryogenic Engineering and International Cryogenic Materials Conference (USA)
 - Proceedings of the International Cryogenic Engineering Conference (Europe/Asia)
- **Data bases**
 - NIST Data base : <http://cryogenics.nist.gov>
 - Cryocomp. Eckels Engineering. 3.06. Cryodata Inc. Florence SC, USA 29501
 - Hepak, Gaspak, MetalPak, Cryodata inc.
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